L Number	Hits	Search Text	DB	Time stamp
161	2594	257/704-707.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:30
162	640	438/125.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:30
163	1076	438/125	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:30
164	1421	257/704	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:31
165	629	257/705	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:31
166	1878	257/706	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:31
167	1509	257/707	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:32
168	4086	257/704 257/705 257/706 257/707	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:32
169	5006	438/125 (257/704 257/705 257/706 257/707)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:33
170	201469	(thermal conductive) near1 (material adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:44
171	883	((thermal conductive) near1 (material adhesive)) with void	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:56
172	18	(438/125 (257/704 257/705 257/706 257/707)) and (((thermal conductive) near1 (material adhesive)) with void)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:36
173	8849	thermally near1 (material adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:55
174	207880	((thermal conductive) near1 (material adhesive)) (thermally near1 (material adhesive))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:55
175	21372	(((thermal conductive) near1 (material adhesive)) (thermally near1 (material adhesive))) with (void hole opening recess)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:58
176	6056	((((thermal conductive) near1 (material adhesive)) (thermally near1 (material adhesive))) with (void hole opening recess)) and (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 14:59
177	1946	(((((thermal conductive) near1 (material adhesive)) (thermally near1 (material adhesive))) with (void hole opening recess)) and (chip die)) and (flipchip (flip adj chip) bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 15:00

178	553	((((((thermal conductive) near1 (material adhesive)) (thermally near1 (material adhesive))) with (void hole opening recess)) and (chip die)) and (flipchip (flip adj chip) bump ball)) and (cap lid heatsink (heat adj sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 15:01
179	506	((((((thermal conductive) near1 (material adhesive)) (thermally near1 (material adhesive))) with (void hole opening recess)) and (chip die)) and (flipchip (flip adj chip) bump ball)) and (cap lid heatsink (heat adj sink))) and (substrate (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 15:03
180	373	(((((((thermal conductive) near1 (material adhesive)) (thermally near1 (material adhesive))) with (void hole opening recess)) and (chip die)) and (flipchip (flip adj chip) bump ball)) and (cap lid heatsink (heat adj sink))) and (substrate (printed adj circuit adj board))) and heat and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 15:04
181	315	((((((((thermal conductive) near1 (material adhesive)) (thermally near1 (material adhesive))) with (void hole opening recess)) and (chip die)) and (flipchip (flip adj chip) bump ball)) and (cap lid heatsink (heat adj sink))) and (substrate (printed adj circuit adj board))) and heat and solder) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/06 15:04